

COATING AGENT SELECTING CHART

○ : Applicable × : Not applicable

Product		Application	Alcohole	Hydrocarbon : NIKKASOLE-RE	Alkali : KILALACLEAN or others	Hot Water ≧ 60°C	Water 25°C
COATING AGENT	BRT Series	Protecting wafer surface during back-grinding process.	×	○	×	×	×
	MA Series	Protecting from scratching of chipping during precision process.	○	×	○	×	×
	NAR Series	Protecting wafer surface during etching process.	○	×	×	×	×
	JK Series	Protecting from scratches and chips during precision process. (can be dried/baked at room temperature)	○	○~×	×	×	×
	SDE Series	Protecting patterned surface of wafer during backside process.	×	○~×	×	×	×
PROTECTLIQUID	N Series	Protecting surface from acid.	×	○	×	×	×
NANOSHELTER	LS Series	Protecting from re-adhering debris.	×	×	×	○	○

Please contact us for details as it may vary depending on the process conditions.

Please refer to SDS of each product for appropriate application and handling before use.